

[54] DUAL HEAT SINK FOR ELECTRONIC
SEMICONDUCTOR DEVICES

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[**] Term: 14 Years

[21] Appl. No.: 252,030

[22] Filed: Apr. 8, 1981

[51] Int. Cl. D13-03

[52] U.S. Cl. D13/23

[58] Field of Search D13/23; 174/16 HS;
357/81; 165/80, 80 A, 80 B

[56] References Cited

U.S. PATENT DOCUMENTS

3,407,868 10/1968 Coe 165/80 B
3,893,161 7/1975 Pesak, Jr. 357/81
4,054,901 10/1977 Edwards et al. 357/81

OTHER PUBLICATIONS

Amperex Transistor Brochure, 6/1966, Extruded Aluminum Heat-Sink.

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[57] CLAIM

The ornamental design for a dual heat sink for electronic semiconductor devices, substantially as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a dual heat sink for electronic semiconductor devices showing my new design; the broken lines being shown for illustrative purposes, only;

FIG. 2 is a front elevational view of the same heat sink;

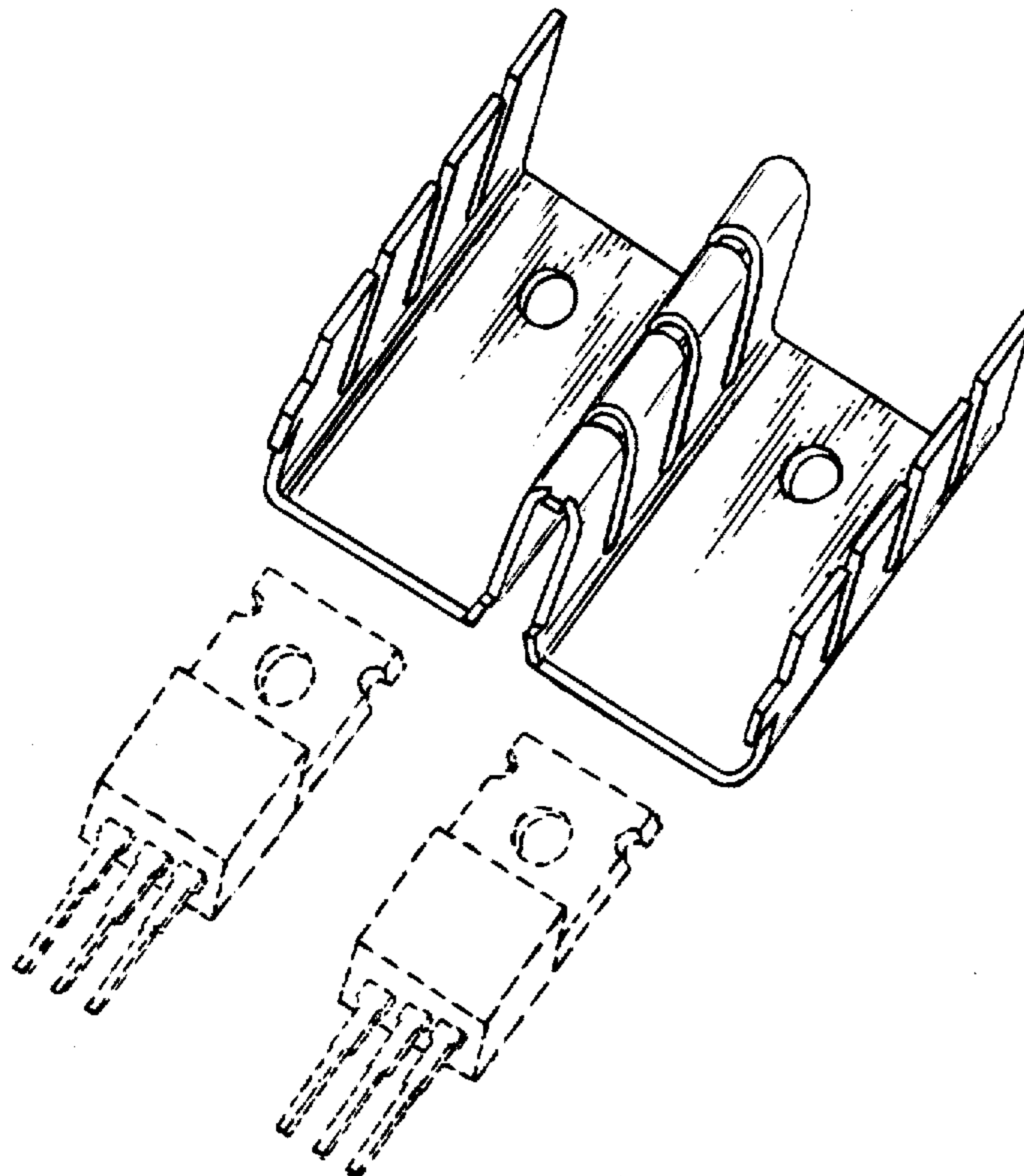
FIG. 3 is a rear elevational view thereof;

FIG. 4 is a side elevational view thereof, looking toward the right side of the heat sink as it is shown in FIG. 1;

FIG. 5 is a side elevational view thereof, looking toward the left side of the heat sink as it is shown in FIG. 1;

FIG. 6 is a top plan view thereof; and

FIG. 7 is a bottom plan view thereof.



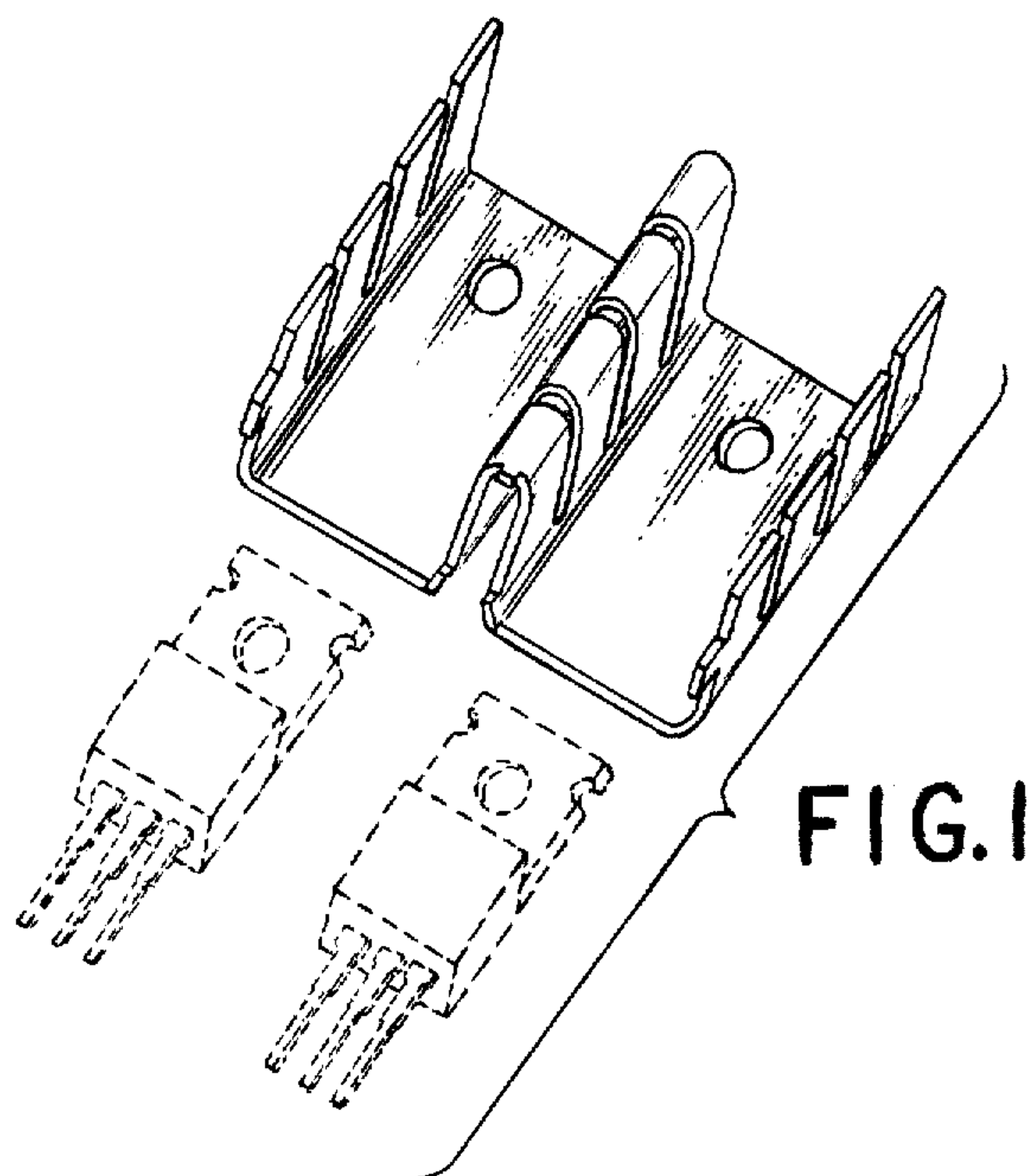


FIG. 1

FIG. 2

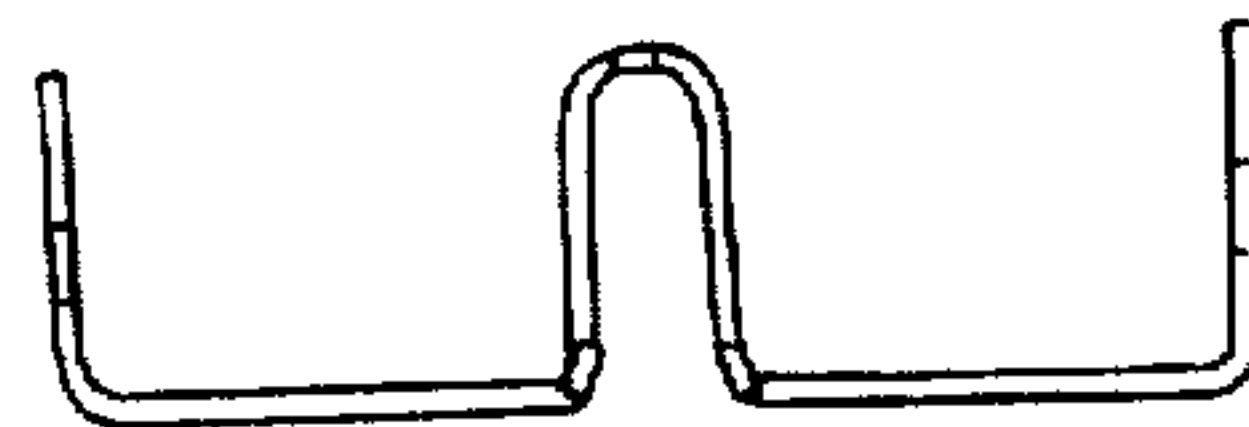


FIG. 3

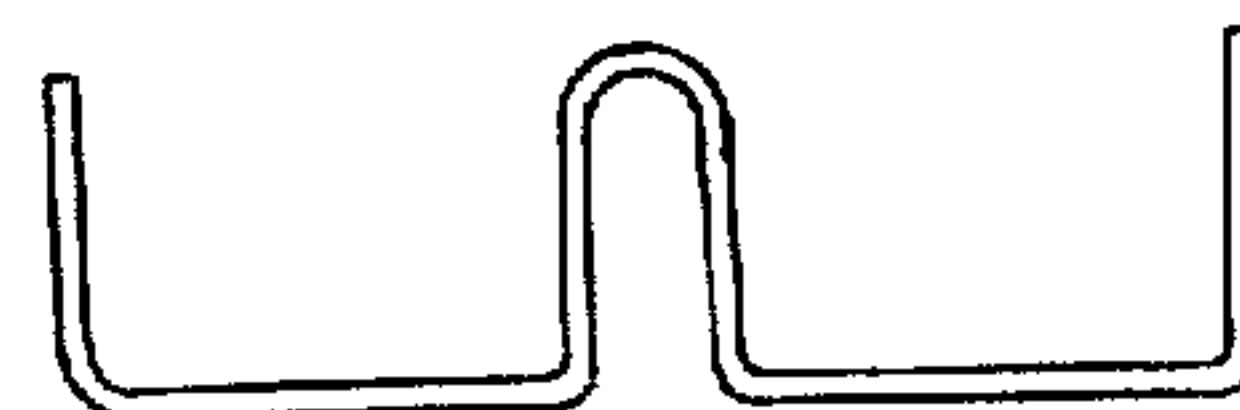


FIG. 4



FIG. 5

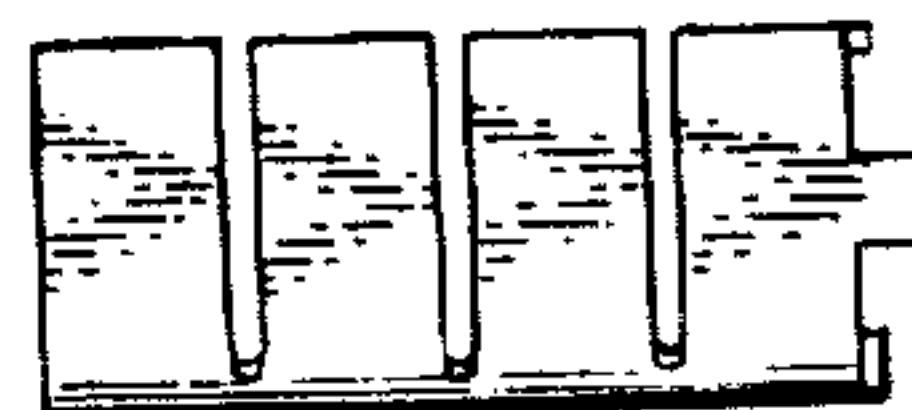


FIG. 6

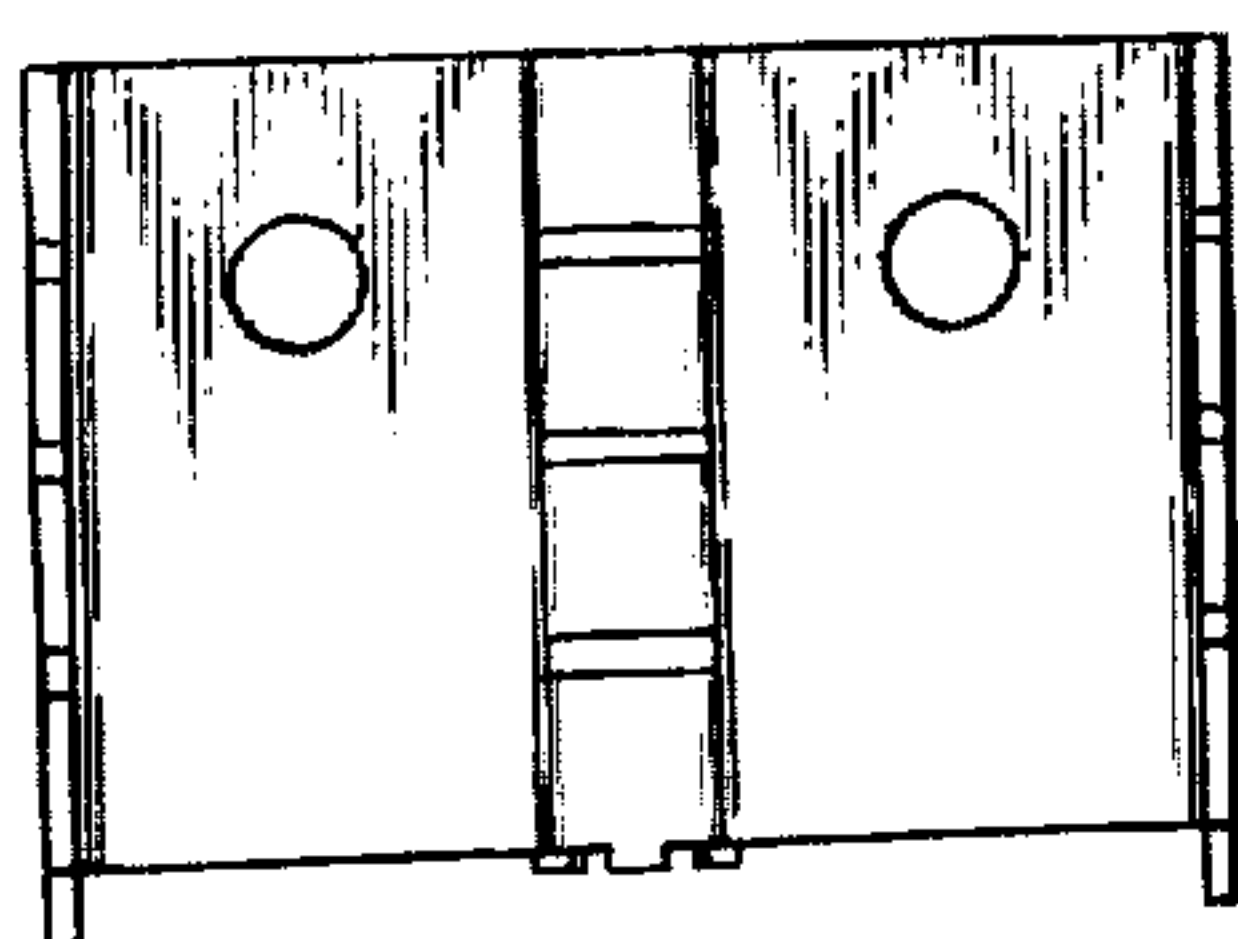


FIG. 7

